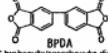
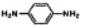
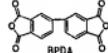
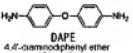
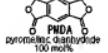
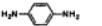
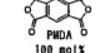
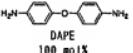
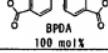
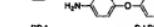
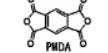
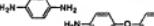
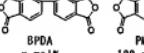
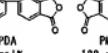
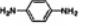
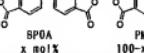
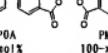
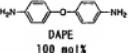
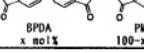
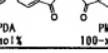
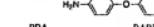


Amendment dated December 2, 2008

Response to September 17, 2008 Non-Final Office Action

AMENDMENTS TO THE SPECIFICATION

Please replace the current chart with the following chart that appears on page 16 of the specification.

Bis(azodicarboxylic acid component	Diamine component		
 BPDA 3,3',4,4'-biphenylene tetracarboxylic dianhydride 100 mol%	 PDA p-phenylenediamine 100 mol%		
 BPDA 100 mol%	 DAPE 4,4'-diaminophenyl ether 100 mol%		
 PMDA pyromellitic dianhydride 100 mol%	 PDA 100 mol%		
 BPDA 100 mol%	 DAPE 100 mol%		
 BPDA 100 mol%	 PDA 75 mol%	 DAPE 25 mol%	
 PMDA 100 mol%	 PDA x mol%	 DAPE 100-x mol%	
 BPDA x mol%	 PMDA 100-x mol%	 PDA 100 mol%	
 BPDA x mol%	 PMDA 100-x mol%	 DAPE 100 mol%	
 BPDA x mol%	 PMDA 100-x mol%	 PDA x mol%	 DAPE 100-x mol%

Please replace the current paragraph 0032 with the following page 18, paragraph 32 in the specification.

In a method for using the adhesive aid composition of the present invention, preferably, the polyimide precursor solution is applied to a substrate so that an imide film has a desired thickness, and dried at 50°C to 150°C for 50 to 180 minutes to prepare a polyimide precursor film. Furthermore On top of that, the adhesive aid composition of the present invention is applied to the precursor film, dried at 50°C to 150°C for 5 to 180 minutes, and then the polyimide precursor is subjected to imidization by heating at 200°C to 500°C for 20 to 300 minutes in a nitrogen stream to prepare a surface-adhesive film. In a system containing the polyimide precursor, a catalyst and a dehydrator, imidization can be performed at a lower temperature or within a shorter time. The resultant film of the present invention is used together with the substrate or after being separated from the substrate.